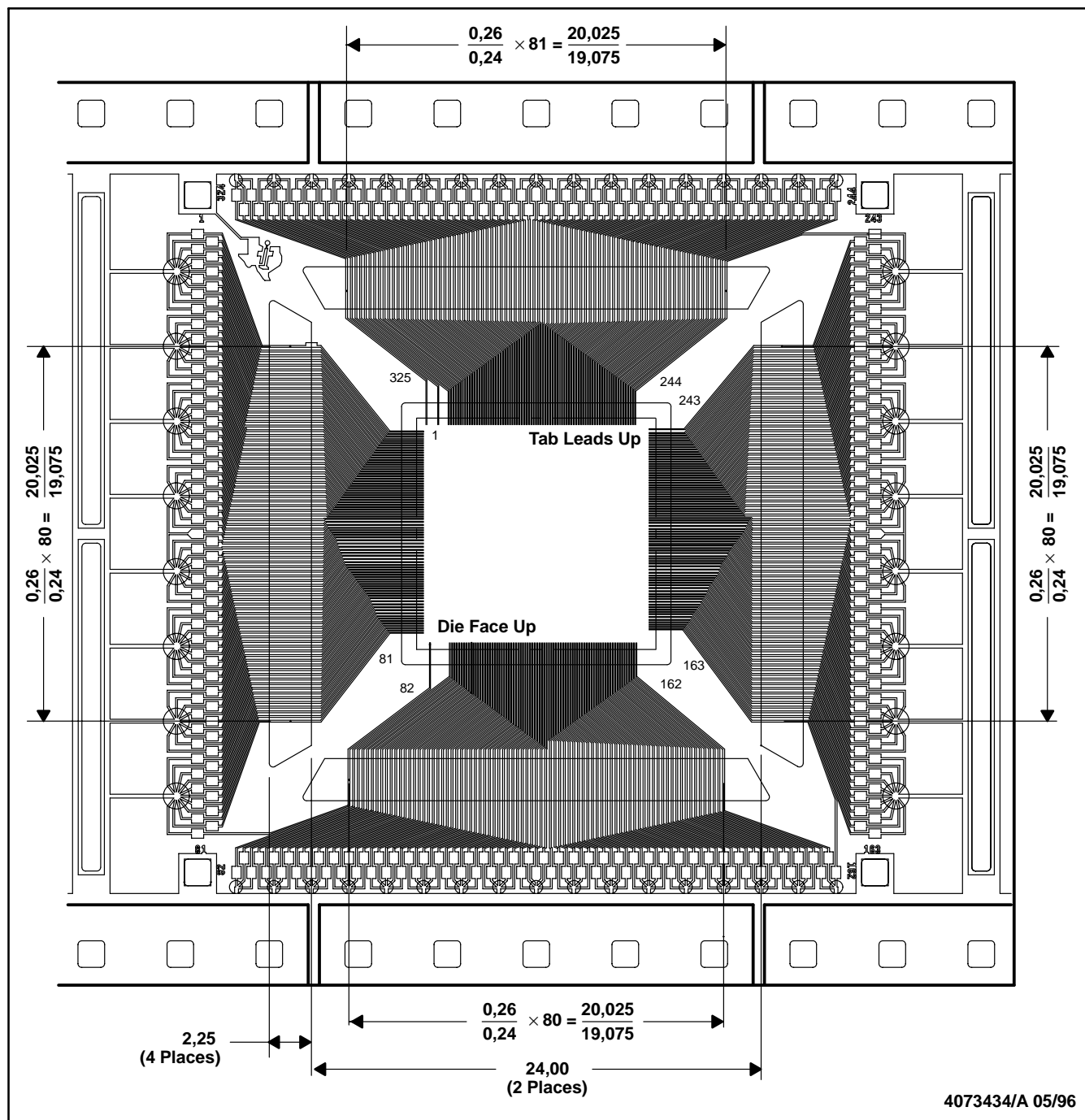


TBB (S-MQCC-F325)
(48 mm WITHOUT PROTECTIVE FILM)

SMJ320C40 324-PIN TAB FRAME SOCKET (PG 5.1)
325 OLB/ILB 0,25 mm OLB PITCH



- NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. The OLB lead width is $0,10 \pm 0,02$ mm.
D. The ILB lead width is $0,05 \pm 0,01$ mm.
E. The tape width is 48 mm.
F. The TBB is bare die.

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